



Material Declaration Data Sheet

Model: **Server System MFSYS25, MFSYS35**

Manufacturer: Intel Corporation

Note: This declaration applies to all associated product codes noted on Page 2

Lead Free (Pb) Product: **No**

Date: February 27, 2009

Restriction on Hazardous Substances (RoHS) Compliance

RoHS Definition

- Quantity limit of 0.1% by mass (1000PPM) for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE)
- Quantity limit of 0.01% by mass (100 PPM) for: Cadmium

Intel understands RoHS requires: Lead and other materials banned in the RoHS Directive are either (1) below all applicable substance thresholds as proposed by the EU or (2) an approved/pending exemption applies. (Note: RoHS implementing details are not fully defined and may change.)

RoHS Declaration

- 1** Lead in glass of cathode ray tubes, electronic components and fluorescent tubes.
- 2** Lead as an alloying element in steel containing up to 0.35 % lead by weight.
- 3** Lead as an alloying element in aluminum containing up to 0.4 % lead by weight.
- 4** Lead as an alloying element in copper containing up to 4 % lead by weight.
- 5** Lead in high melting temperature type solders (i.e. lead based alloys containing 85 % by weight or more lead)
- 6** Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission as well as network management for telecommunications.
- 7** Lead in electronic ceramic parts (e.g. piezoelectronic devices).
- 8** Lead used in compliant pin connector systems.
- 9** Lead as a coating material for the thermal conduction module c-ring.
- 10** Lead in optical and filter glass.
- 11** Lead in solders consisting of more than two parts for the connection between the pins and the package of microprocessors with a lead content of more than 80% and less than 85% by weight.
- 12** Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages.
- 13** Cadmium in optical and filter glass.
- 14** Cadmium and its compounds in electrical contacts and cadmium plating except for applications banned under Directive 91/338/EEC (*) amending Directive 76/769/EEC (**) relating to restrictions on the marketing and use of certain dangerous substances and preparations.
- 15** Lead in bronze bearing shells and brushes.
- 16** Lead in printing inks for application of enamels on borosilicate glass
- 17** Cadmium in printing inks for application of enamels on borosilicate glass
- 18** Lead in Finishes of fine pitch components other than connectors with a pitch of 0.65 mm or less with NiFe lead frames and and lead in finishes of fine pitch components other than connectors with a pitch of 0.65 mm or less with copper lead frames
- 19** Lead in solders for the soldering to machined through hole discoidal and planar array ceramic capacitors
- 20** Lead oxide in plasma display panels (PDP) and surface conduction electron emitter displays (SED) used in structural elements: notably in the front and rear glass dielectric layer, the bus electrode, the black stripe, the address electrode, the barrier ribs, the seal frit, and frit ring as well as in print pastes.
- 21** Other

Where the product is declared to meet RoHS requirements, it has been verified to be in conformance with 2002/95/EC as we currently understand the requirements. Intel has systems in place to verify conformance with all applicable environmental requirements and to the best of our knowledge the information is true and correct.

INTEL ACCEPTS NO DUTY TO UPDATE THIS DECLARATION OR TO NOTIFY USERS OF THIS DECLARATION OF UPDATES OR CHANGES TO THIS DECLARATION. INTEL SHALL NOT BE LIABLE FOR ANY DAMAGES, DIRECT OR INDIRECT, CONSEQUENTIAL OR OTHERWISE, SUFFERED BY USERS OR THIRD PARTIES AS A RESULT OF THE USERS RELIANCE ON INFORMATION IN THIS DECLARATION THAT HAS BEEN UPDATED OR CHANGED.

Product Code Information



| Product Code | Description | *RoHS Exemption # |
|---------------|---|------------------------------|
| AXXGBIOMEZ | Compute Module Mezzanine board | Compliant with no exemptions |
| AXXMFRAIL | Tooless rail kit | Compliant with no exemptions |
| AXXPSU | 1000W Power Supply spare | 1,2,3,4,5,6,7 |
| AXXSCM3S | Intel® Multi-Flex Server Storage Module - SAS | Compliant with no exemptions |
| AXXSW1GB | Intel® Multi-Flex Server GbE Switch Switch | Compliant with no exemptions |
| MFBEZEL | 10 pack standard HDD bay bezel | Compliant with no exemptions |
| MFCMM | Intel® Multi-Flex Server Management Module | Compliant with no exemptions |
| MFHDDBAY25 | 2.5" system 14 drive bay for 2.5 " HDD | Compliant with no exemptions |
| MFIOFAN | I/O fan module | Compliant with no exemptions |
| MFMAINFAN | Main fan module | Compliant with no exemptions |
| MFIDPLANE | Midplane board which includes SD Flash | Compliant with no exemptions |
| MFPSUFAN | Power Slot Cooling Module | Compliant with no exemptions |
| MFS5000SI | Intel® Multi-Flex Server Compute Module | Compliant with no exemptions |
| MFS5000SIB | Intel® Multi-Flex Server Compute Module-Bulk pack | Compliant with no exemptions |
| MFSCMBBU | Storage Battery Backup Unit for Storage Module | Compliant with no exemptions |
| MFSYS25 | Entry system for 2.5" HDD - 6U chassis | 1,2,3,4,5,6,7 |
| MFSYS35 | System for 3.5" HDD – 6U chassis | 1,2,3,4,5,6,7 |
| MFHDDBAY35 | 3.5" system 6 drive bay for 3.5" HDD | Compliant with no exemptions |
| FXX10DVCARBLK | HDD Drive Carrier, 10-pack | Compliant with no exemptions |

* RoHS Exemption # corresponds with exemption #'s found on page 1.